



# PBHV2160Z

600 V, 0.1 A NPN high-voltage low  $V_{CEsat}$  (BISS) transistor

24 June 2015

Product data sheet

## 1. General description

NPN high-voltage low  $V_{CEsat}$  Breakthrough In Small Signal (BISS) transistor in a SOT223 (SC-73) medium power Surface-Mounted Device (SMD) plastic package.

PNP complement: PBHV3160Z

## 2. Features and benefits

- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability
- High collector current gain  $h_{FE}$  at high  $I_C$

## 3. Applications

- Electronic ballast for fluorescent lighting
- LED driver for LED chain module
- LCD backlighting
- HID front lighting
- Hook switch for wired telecom
- Switch Mode Power Supply (SMPS)

## 4. Quick reference data

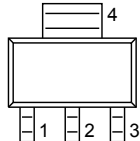
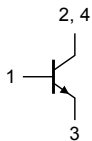
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	600	V
$I_C$	collector current		-	-	0.1	A



## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 <p><b>SC-73 (SOT223)</b></p>	 <p><i>sym016</i></p>
2	C	collector		
3	E	emitter		
4	C	collector		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBHV2160Z	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PBHV2160Z	HV216Z

## 8. Limiting values

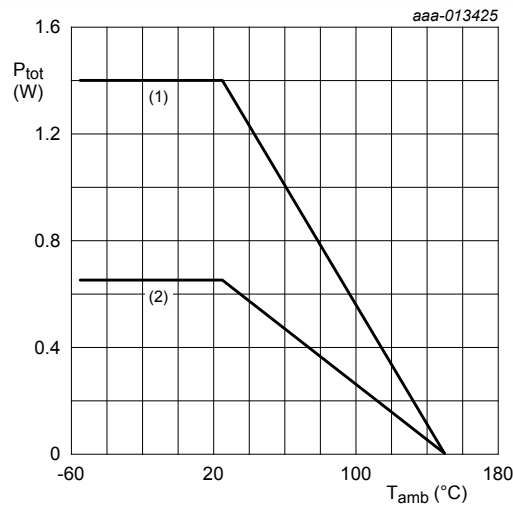
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CBO</sub>	collector-base voltage	open emitter		-	600	V
V <sub>CEO</sub>	collector-emitter voltage	open base		-	600	V
V <sub>CESM</sub>	collector-emitter peak voltage	V <sub>BE</sub> = 0 V		-	600	V
V <sub>EBO</sub>	emitter-base voltage	open collector		-	6	V
I <sub>C</sub>	collector current			-	0.1	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.65	W
			[2]	-	1.4	W
T <sub>j</sub>	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.



(1) FR4 PCB, mounting pad for collector 6 cm<sup>2</sup>

(2) FR4 PCB, standard footprint

**Fig. 1. Power derating curves**

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1]	-	-	190	K/W
			[2]	-	-	89	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point			-	-	20	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

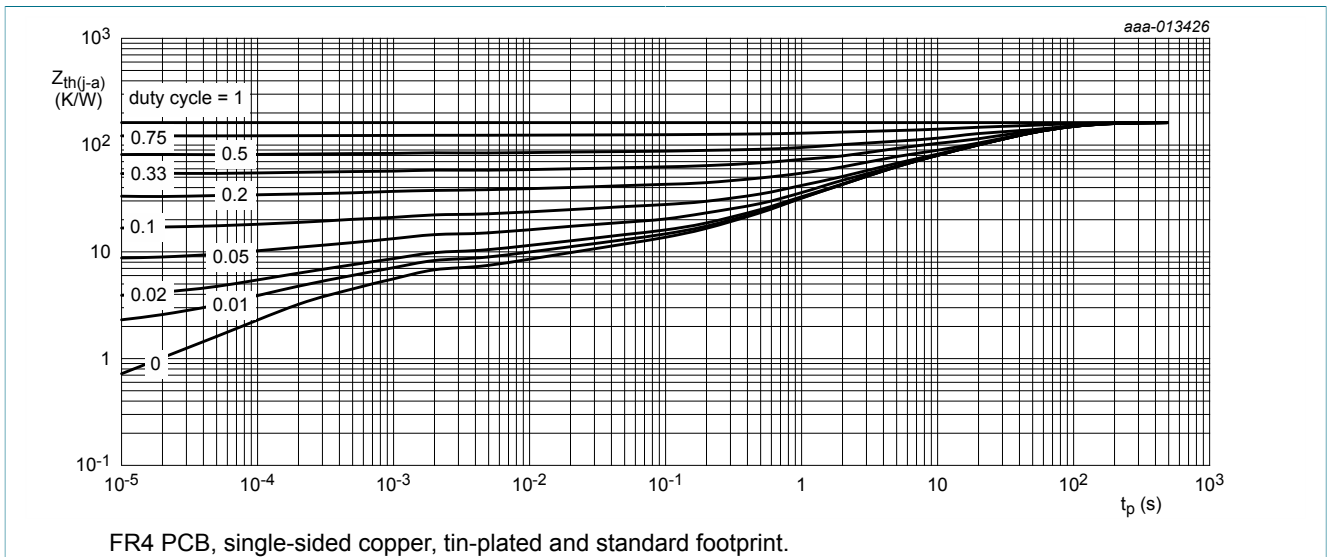


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

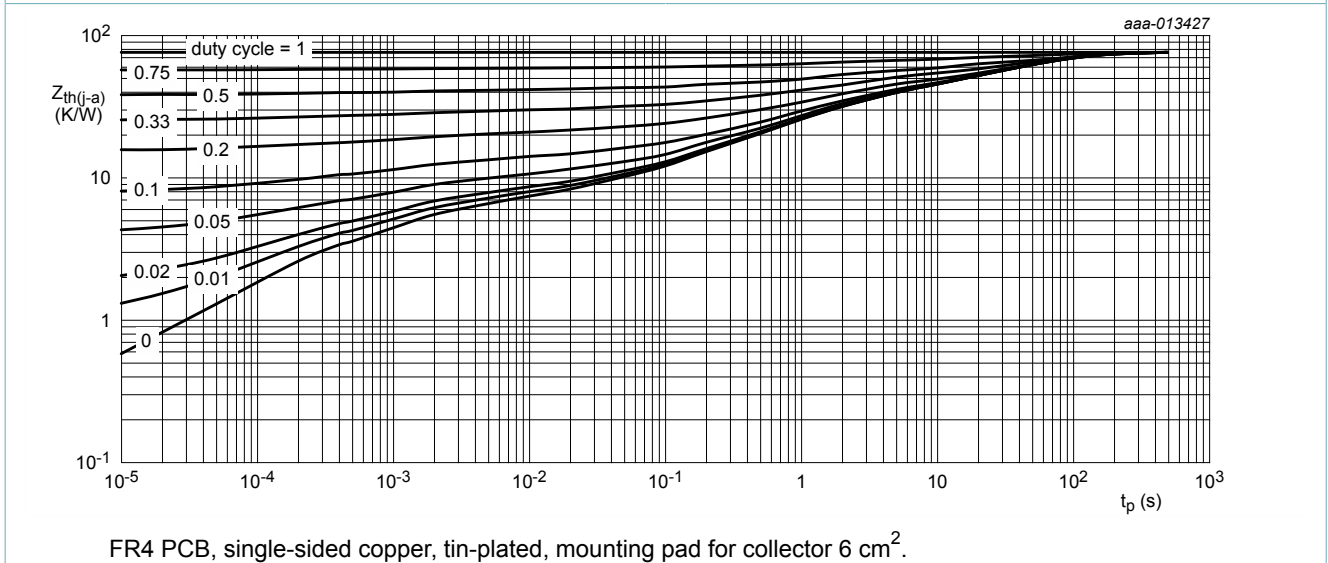
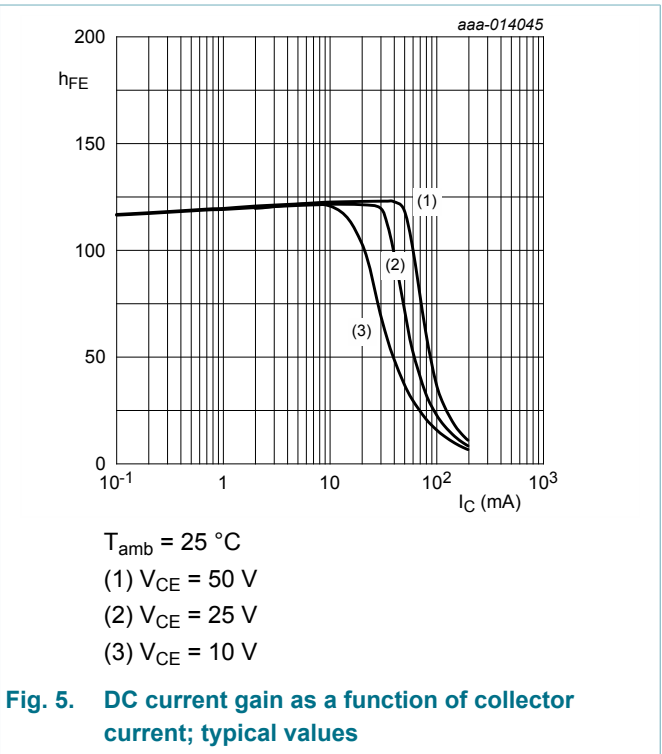
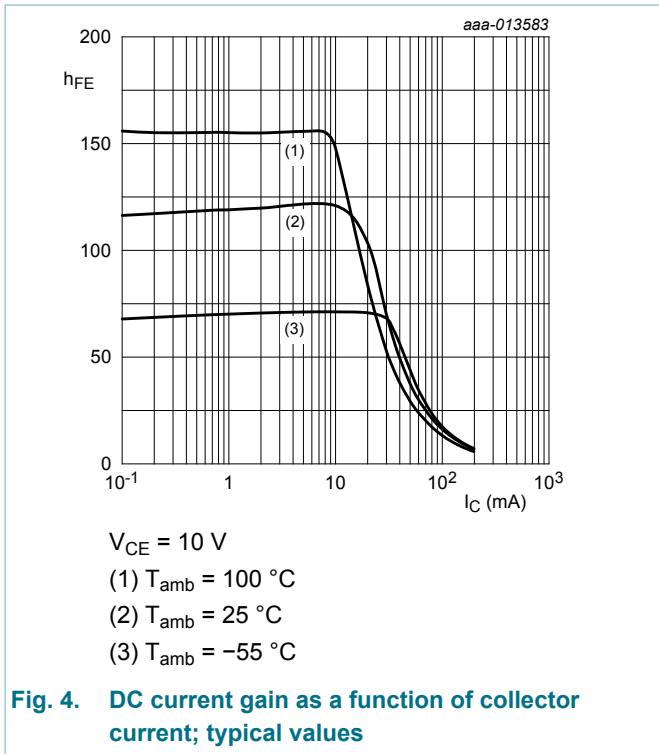


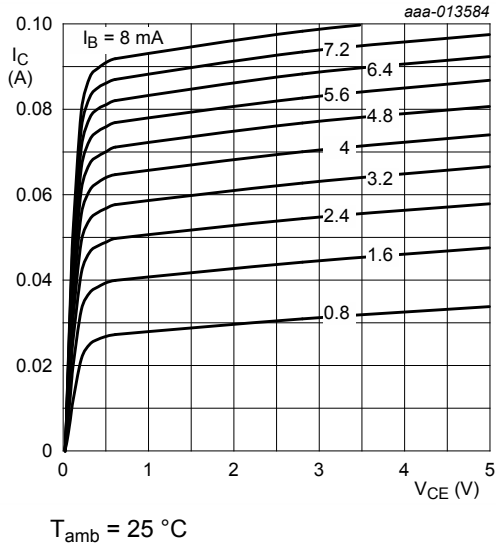
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

### 10. Characteristics

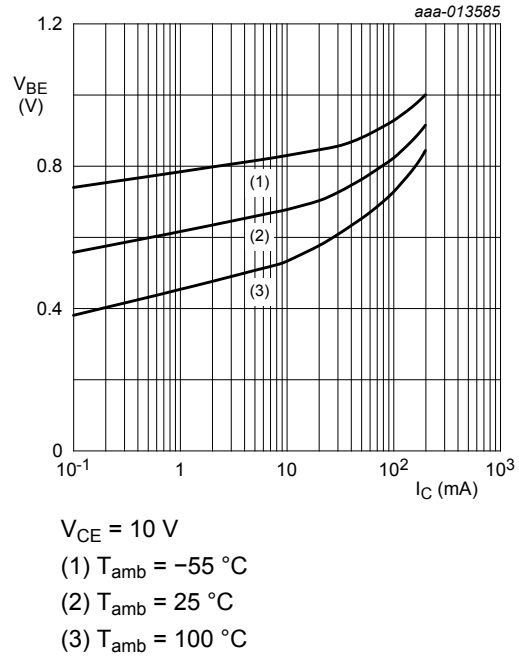
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 400 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	100	nA
		V <sub>CB</sub> = 400 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	10	μA
I <sub>CES</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 400 V; V <sub>BE</sub> = 0 V; T <sub>amb</sub> = 25 °C	-	-	100	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 4.8 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 10 V; I <sub>C</sub> = 10 mA; T <sub>amb</sub> = 25 °C	70	125	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 30 mA; I <sub>B</sub> = 6 mA; T <sub>amb</sub> = 25 °C	-	65	125	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 50 mA; I <sub>B</sub> = 5 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	-	-	950	mV
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = 20 V; I <sub>E</sub> = 0 A; i <sub>e</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	1.7	-	pF
C <sub>e</sub>	emitter capacitance	V <sub>EB</sub> = 0.5 V; I <sub>C</sub> = 0 A; i <sub>c</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	81	-	pF

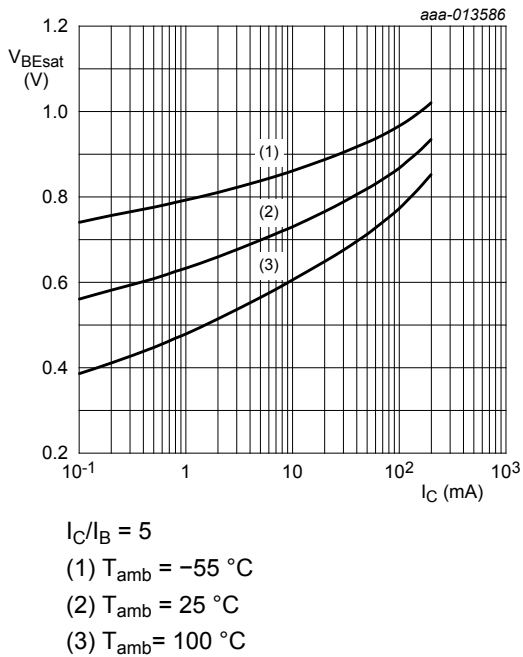




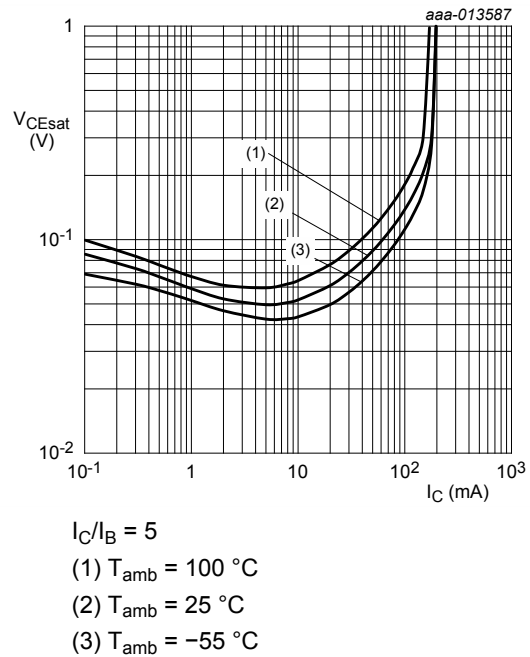
**Fig. 6. Collector current as a function of collector-emitter voltage; typical values**



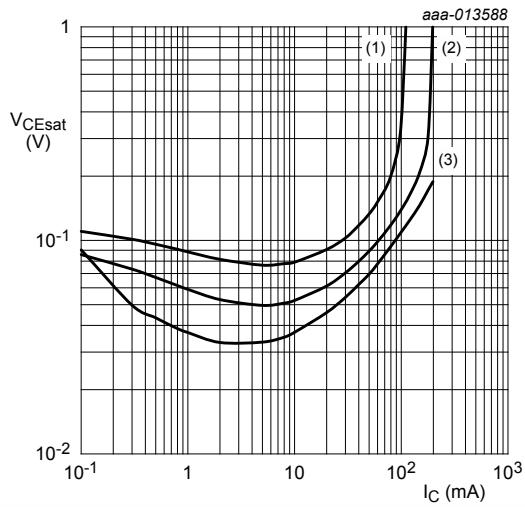
**Fig. 7. Base-emitter voltage as a function of collector current; typical values**



**Fig. 8. Base-emitter saturation voltage as a function of collector current; typical values**

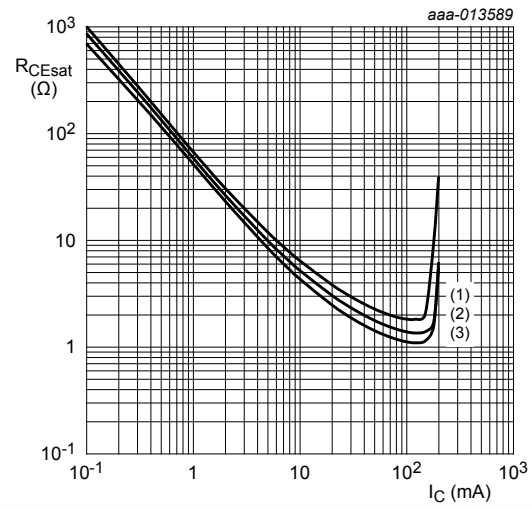


**Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values**



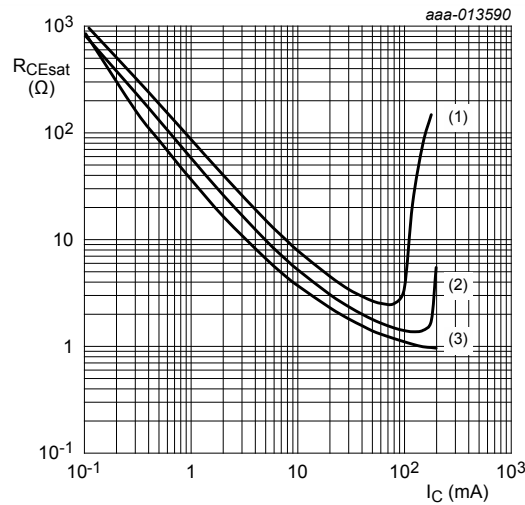
$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 10$   
 (2)  $I_C/I_B = 5$   
 (3)  $I_C/I_B = 2.5$

**Fig. 10. Collector-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 5$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig. 11. Collector-emitter saturation resistance as a function of collector current; typical values**



$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 10$   
 (2)  $I_C/I_B = 5$   
 (3)  $I_C/I_B = 2.5$

**Fig. 12. Collector-emitter saturation resistance as a function of collector current; typical values**

### 11. Package outline

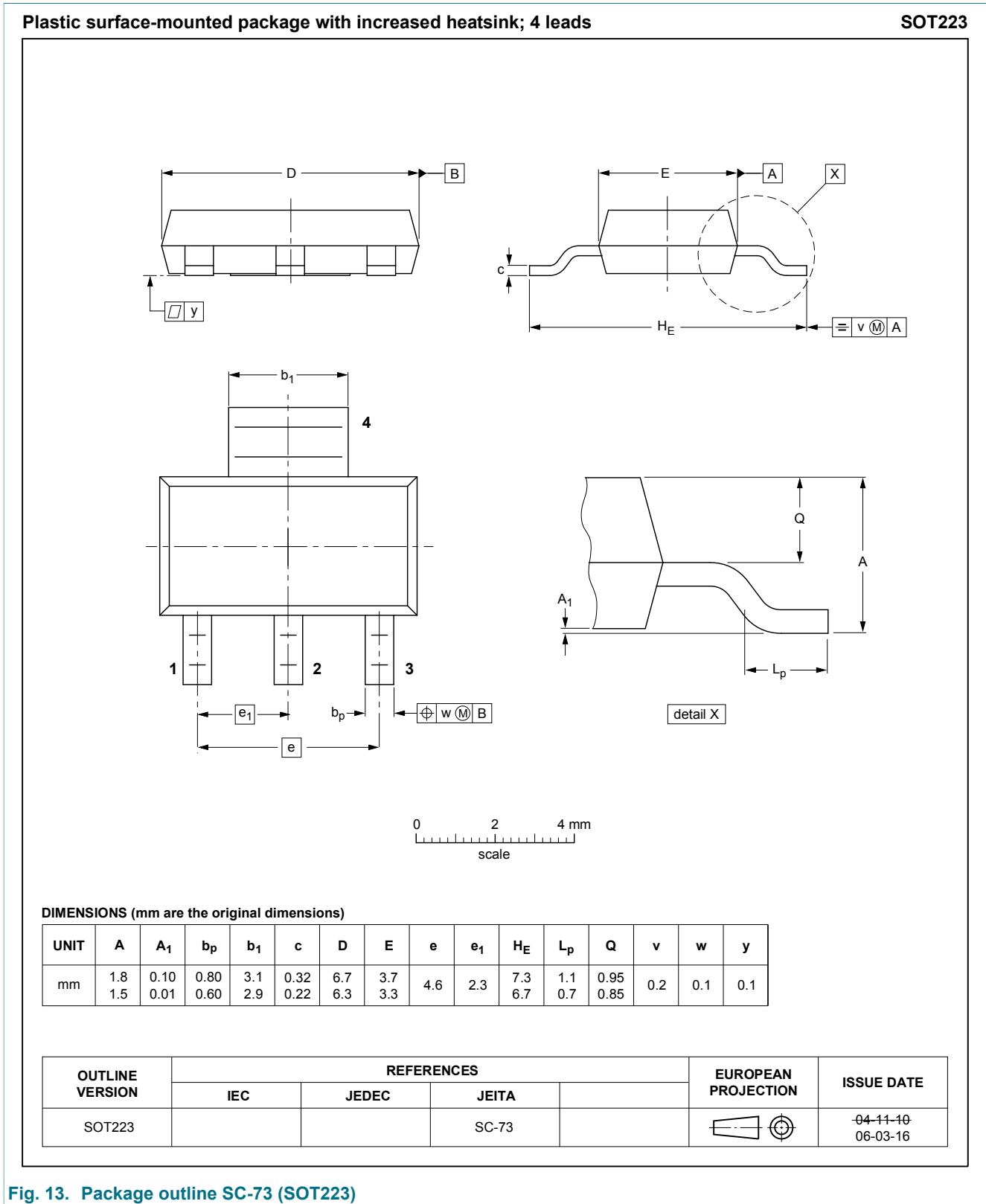


Fig. 13. Package outline SC-73 (SOT223)



## 12. Soldering

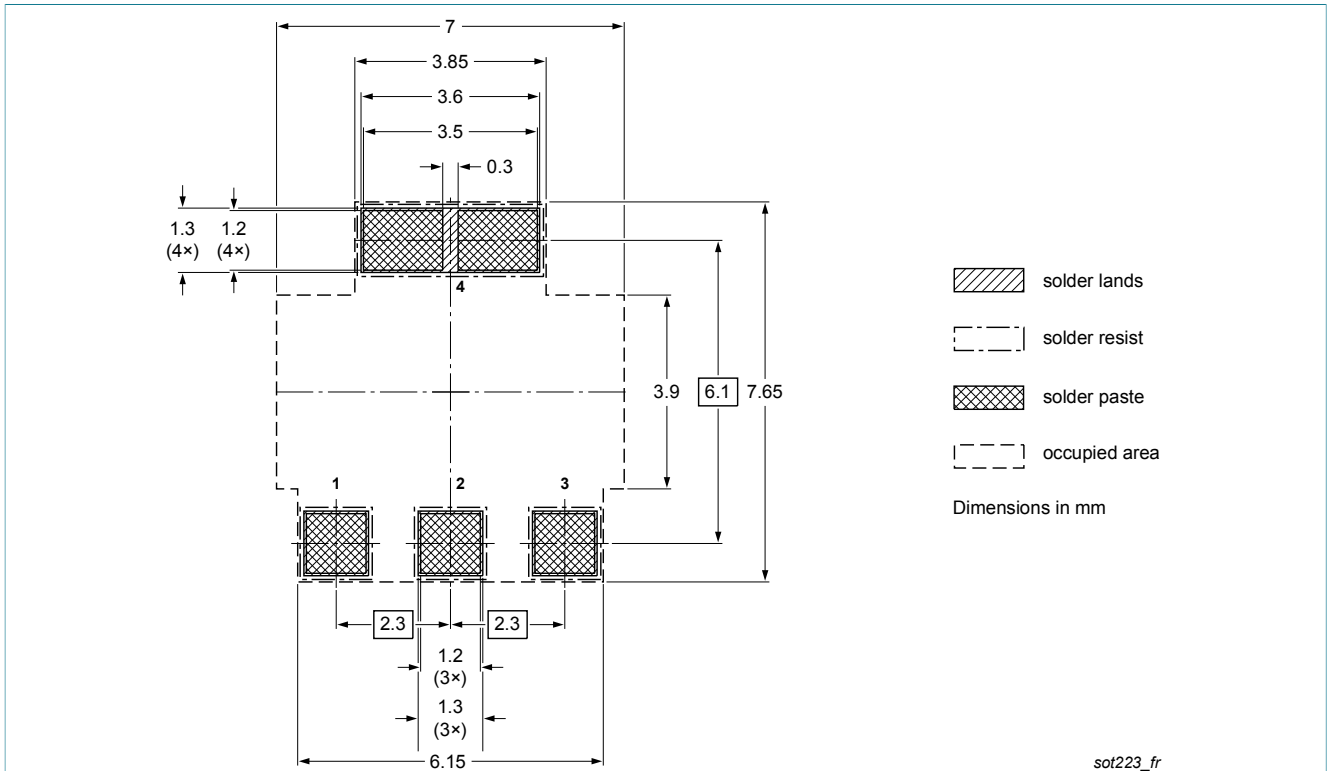


Fig. 14. Reflow soldering footprint for SC-73 (SOT223)

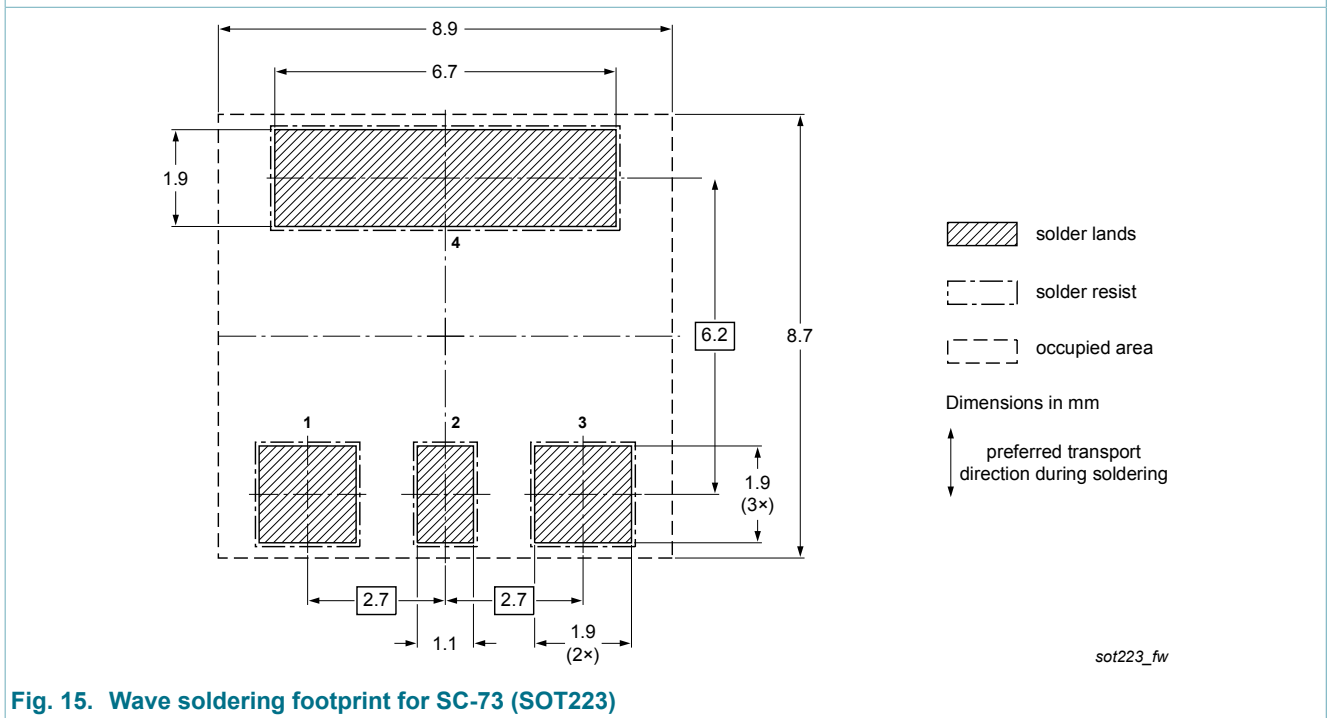


Fig. 15. Wave soldering footprint for SC-73 (SOT223)

## 13. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBHV2160Z v.1	20150624	Product data sheet	-	-

## 14. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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## 15. Contents

1	General description .....	1
2	Features and benefits .....	1
3	Applications .....	1
4	Quick reference data .....	1
5	Pinning information .....	2
6	Ordering information .....	2
7	Marking .....	2
8	Limiting values .....	3
9	Thermal characteristics .....	4
10	Characteristics .....	5
11	Package outline .....	8
12	Soldering .....	9
13	Revision history .....	10
14	Legal information .....	11
14.1	Data sheet status .....	11
14.2	Definitions .....	11
14.3	Disclaimers .....	11
14.4	Trademarks .....	12

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